S36	5	S34 and (pair near2 (short open load) near2 circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:29
S37	4	S36 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 11:39
S38	2	("5047752").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 11:44
S39	11	(324/601.ccls.) and @ad<"20030923" and @pd>"20041222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:56
S40	5	(324/600.ccls.) and @ad<"20030923" and @pd>"20041222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:59
S41	524	(324/130,202.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:06
S42	1365	(324/74,76.11.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:06

S43	5275	(324/754-758.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:51
S44	9	S43 and ((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) ISS)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:12
S45	3	((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) ISS) same (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) same calibrat$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:16
S46	1	S45 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:18
S47	11	((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) ISS) same (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) same ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 09:21
S48	8	S47 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:23
S49	3395	((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) ISS) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:52

S50	125	S49 and (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) same ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:24
S51	16	(impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:23
S52	16	S51 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:23
S53	3	S52 and (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) same ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:04
S54	3394	(impedance adj standard adj substrate "ISS") and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 10:20
S55	15	(impedance adj standard adj substrate) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:03
S56	44	S54 and (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) with ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 09:14

S57	2	("4,994,737").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 08:53
S58	1697	(702/57,65,91,117,168.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:51
S59	2	S58 and ((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane) ISS)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:54
S60	1	S57 and ((impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane) ISS)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 08:56
S61	2	("4,858,160").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 08:56
S62	1	S55 and (oscill$7 VNA (vector$5 adj network$3 adj anal$5)) with ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 09:15
S63	21	((impedance adj standard) same (oscill$7 VNA (network$3 adj anal$5)) same ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:21

S64	2	("4,697,143").PN.		OR	OFF	2005/06/08 10:05
S65	25	(impedance adj standard adj (substrate assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 10:23
S66	1	("338"/$.ccls.) and ((impedance resist$5) adj standard adj (substrate assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:21
S67	77	((impedance resist$5) adj standard adj (substrate assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:13
S68	68	S67 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:14
S69	4549	(324/158.1.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:20
S70	149	S69 and (oscill$7 VNA (network$3 adj anal$5)) same ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:22

S71	186	("338"/$.ccls.) and (oscill$7 VNA (network$3 adj anal$5)) same (($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:47
S72	1	S71 and (impedance resist$5) adj standard	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:25
S73	21	S70 and ((short open load) near2 circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:27
S74	24	S71 and ((short open load) near2 circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:32
S75	70310	((oscill$7 VNA (network$3 adj anal$5)) near5 ($2adjust$ regulat$3 fit$4 chang$3 calibrat$5)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 11:47
S76	6115	S75 and ((short open load) near2 circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:49
S77	115	S76 and substrate same contact same surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:37

S78	19	S76 and substrate same contact same surface same via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:37
S79	26	(impedance adj standard adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment cell)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:51
S80	12	S79 and ((open adj circuit) open$1circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 12:51
S81	4	S80 and ((short adj circuit) short$1circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/08 14:44
S82	4	(("3768157") or ("5760336")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 14:46
S83	18	("2103040" | "3080481" | "3217088" | "3340602" | "3383454" | "3388461" | "3497947" | "3534472" | "3535778").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 16:29